# Winstar Display Co., LTD





住址: **407** 台中市中清路 **163** 號 No.163 Chung Ching RD., Taichune, Taiwan, R.O.C

**CUSTOMER** 

**ISSUED DATE:** 

WEB: <a href="http://www.winstar.com.tw">http://www.winstar.com.tw</a>
E-mail: winstar@winstar.com.tw
Tel:886-4-24262208 Fax: 886-4-24262207

### **SPECIFICATION**

MODULE	MODULE NO.:		WH0802A-TMI-CT					
APPROV	ED BY:							
( FOR CUSTOME	R USE ONLY)							
		PCB V	VERSION:		DATA:			
SALES BY	APPROVED	BY	CHECKED	BY	PREPARED BY			



MODLE NO:		

REC	ORDS OF REV	ISION		DOC. FIRST ISSUE
VERSION	DATE	REVISED PAGE NO.	SUI	MMARY
0	2005-12-23		Fin	est issue
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### 1.Module Classification Information

$$\underline{W} \underline{H}$$
 $\underline{0} \underline{8} \underline{0} \underline{2}$ 
 $\underline{A} - \underline{T} \underline{M} \underline{I}$ 
 $\underline{C} \underline{T}$ 
 $\underline{S}$ 
 $\underline{S}$ 
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① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type

3 Display Font: Character 8 words, 2Lines.

Model serials no.

 $\ \$  Backlight Type : N $\rightarrow$ Without backlight A $\rightarrow$ LED, Amber

 $B \rightarrow EL$ , Blue green  $R \rightarrow LED$ , Red  $D \rightarrow EL$ , Green  $O \rightarrow LED$ , Orange  $W \rightarrow EL$ , White  $G \rightarrow LED$ , Green  $F \rightarrow CCFL$ , White  $T \rightarrow LED$ , White

Y→LED, Yellow Green

© LCD Mode : B→TN Positive, Gray T→FSTN Negative

N→TN Negative,

G→STN Positive, Gray

Y→STN Positive, Yellow Green

M→STN Negative, Blue

F→FSTN Positive

② LCD Polarizer A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00 range/ View G→Reflective W.T. 6:00 C→Transmissive N.T. 6:00

range/ View direction  $G \rightarrow \text{Reflective}$ , W. T, 6:00  $C \rightarrow \text{Transmissive}$ , N.T,6:00  $J \rightarrow \text{Reflective}$ , W. T, 12:00  $F \rightarrow \text{Transmissive}$ , N.T,12:00

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00

E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code
CT : English and Cyrillic standard font

### 2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.

## 3.General Specification

Item	Dimension	Unit
Number of Characters	8 characters x 2 Lines	_
Module dimension	58.0 x 32.0 x 13.3(MAX)	mm
View area	38.0 x 16.0	mm
Active area	27.81 x 11.5	mm
Dot size	0.56 x 0.66	mm
Dot pitch	0.60 x 0.70	mm
Character size	2.96 x 5.56	mm
Character pitch	3.55 x 5.94	mm
LCD type	STN Negative, Blue Transmissive	,
Duty	1/16	
View direction	6 o'clock	
Backlight Type	LED, White	

# 4. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	$T_{OP}$	20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	$T_{ST}$	-30	_	+80	$^{\circ}\! \mathbb{C}$
Input Voltage	$V_{\rm I}$	$V_{SS}$	_	$V_{DD}$	V
Supply Voltage For Logic	$V_{ m DD} ext{-}V_{ m SS}$	-0.3	_	5	V
Supply Voltage For LCD	$V_{\mathrm{DD}}$ - $V_{\mathrm{0}}$	-0.3	_	4.2	V

# 5.Electrical Characteristics

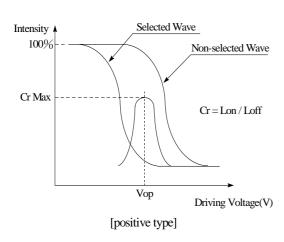
Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$	_	4.5	5.0	5.5	V
		Ta=-20°C	_	_	5.5	V
Supply Voltage For LCD	$V_{DD}$ - $V_0$	Ta=25°℃	_	4.4	_	V
		Ta=70°C	3.5	_	_	V
Input High Volt.	$V_{\mathrm{IH}}$	_	$0.7~V_{DD}$	_	$V_{\mathrm{DD}}$	V
Input Low Volt.	$V_{\rm IL}$	_	VSS	_	0.6	V
Output High Volt.	$V_{\mathrm{OH}}$	_	3.9	_	_	V
Output Low Volt.	$V_{OL}$	_	_	_	0.4	V
Supply Current	$I_{DD}$	V <sub>DD</sub> =5V	1.0	1.2	1.5	mA

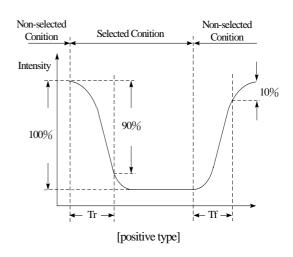
## 6.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V) θ	CR≧2	20	_	40	deg
, ie w i mgie	(H) φ	CR≧2	-30	_	30	deg
Contrast Ratio	CR	_	_	3	_	_
Response Time	T rise	_	_	150	200	ms
	T fall	_	—	150	200	ms

### **Definition of Operation Voltage (Vop)**

#### **Definition of Response Time (Tr, Tf)**





#### **Conditions:**

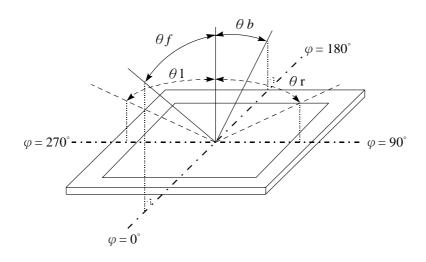
Operating Voltage: Vop

Viewing Angle( $\theta$ ,  $\varphi$ ):  $0^{\circ}$ ,  $0^{\circ}$ 

Frame Frequency: 64 HZ

Driving Waveform: 1/N duty, 1/a bias

### Definition of viewing angle( $CR \ge 2$ )

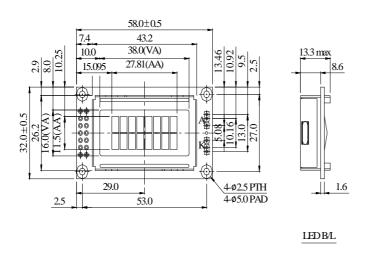


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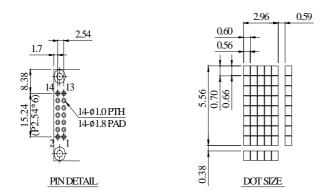
# 7.Interface Pin Function

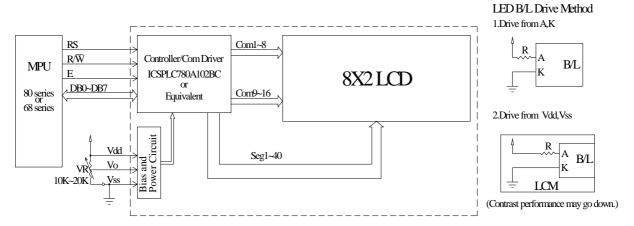
Pin No.	Symbol	Level	Description
1	$V_{SS}$	0V	GND
2	$V_{\mathrm{DD}}$	5.0V	Supply Voltage for logic
3	VO	(Variable)	Contrast Adjustment
4	RS	H/L	Resigter select signal
5	R/W	H/L	H: Read(MPU→Module) L: Write(MPU→Module)
6	Е	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line

## 8.Contour Drawing & Block Diagram



PIN NO.	SYMBOL
1	Vss
2	Vdd
3	Vo
4	RS
5	R/W
6	Е
7	DB0
8	DB1
9	DB2
10	DB3
11	DB4
12	DB5
13	DB6
14	DB7





External contrast adjustment.

Character located 1 2 3 4 5 6 7 8

DDRAM address | 00 01 02 03 04 05 06 07

DDRAM address | 40 41 42 43 44 45 46 47

### 9. Function Description

The LCD display Module is built in a LSI controller, the controller has two 8-bit registers, an instruction register (IR) and a data register (DR).

The IR stores instruction codes, such as display clear and cursor shift, and address information for display data RAM (DDRAM) and character generator (CGRAM). The IR can only be written from the MPU. The DR temporarily stores data to be written or read from DDRAM or CGRAM. When address information is written into the IR, then data is stored into the DR from DDRAM or CGRAM. By the register selector (RS) signal, these two registers can be selected.

RS	R/W	Operation
0	0	IR write as an internal operation (display clear, etc.)
0	1	Read busy flag (DB7) and address counter (DB0 to DB7)
1	0	Write data to DDRAM or CGRAM (DR to DDRAM or CGRAM)
1	1	Read data from DDRAM or CGRAM (DDRAM or CGRAM to DR)

#### **Busy Flag (BF)**

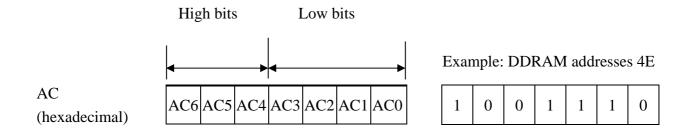
When the busy flag is 1, the controller LSI is in the internal operation mode, and the next instruction will not be accepted. When RS=0 and R/W=1, the busy flag is output to DB7. The next instruction must be written after ensuring that the busy flag is 0.

#### Address Counter (AC)

The address counter (AC) assigns addresses to both DDRAM and CGRAM

#### **Display Data RAM (DDRAM)**

This DDRAM is used to store the display data represented in 8-bit character codes. Its extended capacity is 80×8 bits or 80 characters. Below figure is the relationships between DDRAM addresses and positions on the liquid crystal display.



#### Display position DDRAM address

1 2 3 4 5 6 7 8

00	01	02	03	04	05	06	07				
40	41	42	43	44	45	46	47				

2-Line by 8-Character Display

#### **Character Generator ROM (CGROM)**

The CGROM generate 5×8 dot or 5×10 dot character patterns from 8-bit character codes. See Table 2.

#### **Character Generator RAM (CGRAM)**

In CGRAM, the user can rewrite character by program. For  $5\times8$  dots, eight character patterns can be written, and for  $5\times10$  dots, four character patterns can be written.

Write into DDRAM the character code at the addresses shown as the left column of table 1. To show the character patterns stored in CGRAM.

### Relationship between CGRAM Addresses, Character Codes (DDRAM) and Character patterns

Table 1.

For 5 \* 8 dot character patterns

Character Codes (DDRAM data)	CGRAM Address	C haracter Patterns (CGRAM data)	
7 6 5 4 3 2 1 0	5 4 3 2 1 0	7 6 5 4 3 2 1 0	
High Low	High Low	High Low	
0 0 0 0 * 0 0 0	0 0 0 0 0 0 0 1 0 0 1 0 0 1 1 0 0 1 1 0 1 1 1 1 0 1 1 1 1 0 1 1 1 1 0 1 1 1 1 1 0 1 1 1 1 1 0 1 1 1 1 1 0 1	* * * * 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	Character pattern(1)
0 0 0 0 * 0 0 1	0 0 0 0 0 1 0 1 0 0 1 1 0 0 1 1 0 0 1 0 1 1 1 0 1 1 1 0 0 0	* * * * * * * * * * * * * * * * * * *	Character pattern(2)  Cursor pattern
	0 0 0		
0 0 0 0 * 1 1 1	1 1 1 1 0 0 1 0 1 1 1 0 1 1 1	* * *	

For 5 \* 10 dot character patterns

Character Codes (DDRAM data)		RAM Address	Character Patterns (CGRAM data)	
7 6 5 4 3 2 1 0	:	5 4 3 2 1 0	7 6 5 4 3 2 1 0	
High Low	Hig	g h L o w	High Low	
0 0 0 0 * 0 0 0		0 0 0 0 0 0 0 0 0 0 0 1 0 0 0 1 1 0 0 0 0 1 0 0 0 0 1 0 0 0 0 1 1 1 1 1 1 1 0 0 0 0 1 1 0 0 1 0 0 1 1 0 0 0 1 1 0 0 0 1 1 0 0 0 1 1 0 0 0 1 1 0 0 0 0 1 1 0	* * * * 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	C haracter pattern  C ursor pattern
		1 1 1 1	* * * * * * * *	

■ : " High "

# 10.Character Generator ROM Pattern

Table.2

Upper 4 bit	1111	1111	1111	11111	1 111 1	1 111 11	1 1111	1 11111	шп	шти	ш ш	ит ии	ии т	иш и	пппі	нннн
Lower 4 bit		LLLII	LLIIL	LLIIII	LIILL	LIILII	LIIIL	LIIIIII	IILLL	IIILLII	IILIIL	IILIIII	IIIILL	IIIILII	IIIIIIL	11111111
LLLL	CG RAM (1)					::::: :	••	<b>:</b> -						=		
LLLH	CG RAM (2)		=				-:::	-:::						1		
LLHL	CG RAM (3)		= =	- ";				:					*****	::		•
LLHH	CG RAM (4)				<b></b>	=====	ŧ	-:::-				====	11	::		
LHLL	CG RAM (5)							·				=====	: :			
LHLH	CG RAM (6)			****			====	<b>.</b>								**
LHHL	CG RAM (7)		:	=====		ii		ii								
LННН	CG RAM (8)		==	:				II			-::;		-:::		-	
HLLL	CG RAM (1)		ŧ	=====		:	<b>!</b> :	:-: <u>'</u>				ii	-::		-	
HLLH	CG RAM (2)					• • •					i		:-;:-		-""	
HLHL	CG RAM (3)			==	!		:					<b>!-:</b>	:: ::		====	
нцнн	CG RAM (4)		[	::			i					- : :			===-	
HHLL	CG RAM (5)		<u>:</u>	-::	i i							ii		-11-1		
HHLH	CG RAM (6)						["-"]						===-		-	
нннг	CG RAM (7)		==			<sup>-</sup>	i-''i	-=:-=								
нннн	CG RAM (8)						::							==	====	

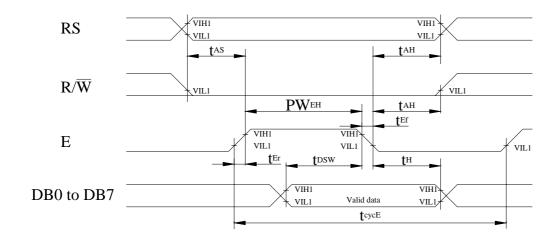
# 11.Instruction Table

Instruction				Ins	structi	on Co	de				Description	Execution time
instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	(fosc=270Khz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "00H" to DDRAM and set DDRAM address to "00H" from AC	1.53ms
Return Home	0	0	0	0	0	0	0	0	1	l	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.53ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	SH	Assign cursor moving direction and enable the shift of entire display.	39 μ s
Display ON/OFF Control	0	0	0	0	0	0	1	D	C	В	Set display (D), cursor (C), and blinking of cursor (B) on/off control bit.	39 μ s
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	_	_	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	39 μ s
Function Set	0	0	0	0	1	DL	N	F	-		Set interface data length (DL:8-bit/4-bit), numbers of display line (N:2-line/1-line)and, display font type (F:5×11 dots/5×8 dots)	39 μ s
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	39 μ s
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter.	39 μ s
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0 μ s
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	43 μ s
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	43 μ s

**\*** "−" : don't care

# 12. Timing Characteristics

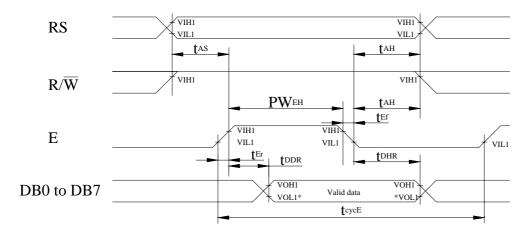
### 12.1 Write Operation



Ta=25°C, VDD=5.0± 0.5V

Item	Symbol	Min	Тур	Max	Unit
Enable cycle time	$t_{\rm cycE}$	1200	_	_	ns
Enable pulse width (high level)	$PW_{EH}$	140	=	_	ns
Enable rise/fall time	$t_{\rm Er}, t_{\rm Ef}$	=	=	25	ns
Address set-up time (RS, R/W to E)	$t_{AS}$	0	=	_	ns
Address hold time	$t_{AH}$	10	=	_	ns
Data set-up time	$t_{DSW}$	40	=	_	ns
Data hold time	t <sub>H</sub>	10	_	_	ns

### 12.2 Read Operation

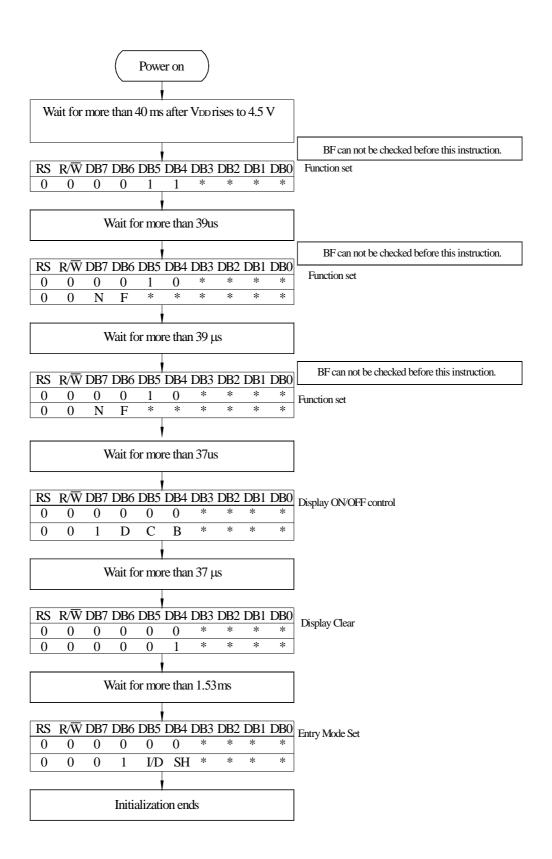


NOTE: \*VOL1 is assumed to be 0.8V at 2 MHZ operation.

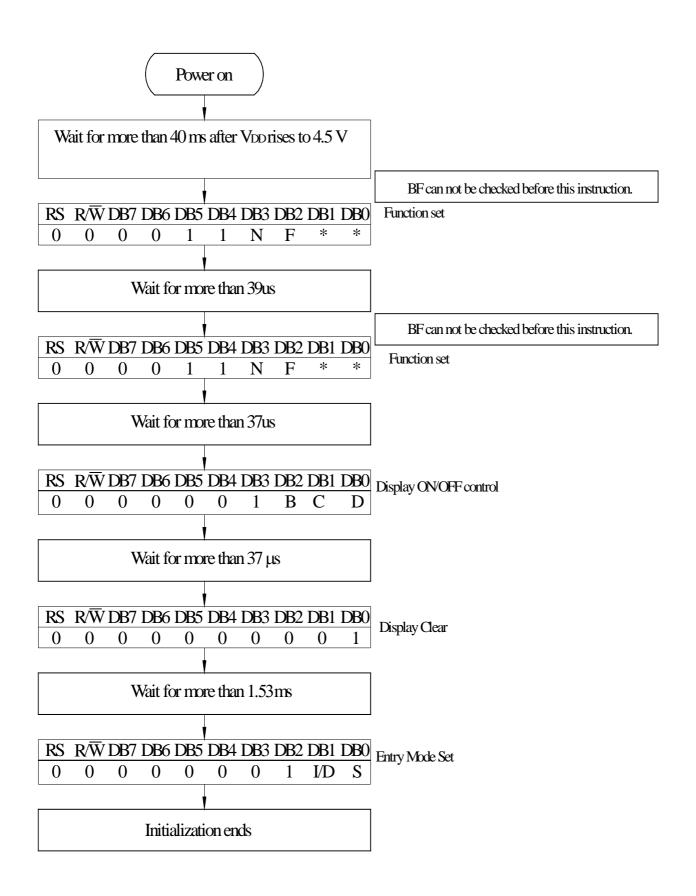
 $Ta=25^{\circ}C$ ,  $VDD=5.0\pm0.5V$ 

Item	Symbol	Min	Тур	Max	Unit
Enable cycle time	$t_{ m cycE}$	1200	_	_	ns
Enable pulse width (high level)	$PW_{EH}$	140	_	_	ns
Enable rise/fall time	$t_{\rm Er}, t_{\rm Ef}$	_	_	25	ns
Address set-up time (RS, R/W to E)	$t_{AS}$	0	_	_	ns
Address hold time	$t_{AH}$	10	=	=	ns
Data delay time	t <sub>DDR</sub>	_	_	100	ns
Data hold time	t <sub>DHR</sub>	10			ns

## 13.Initializing of LCM



4-Bit Ineterface



8-Bit Ineterface

## 14. Reliability

Content of Reliability Test (wide temperature, -20°C~70°C)

	<b>Environmental Test</b>		
Test Item	Content of Test	<b>Test Condition</b>	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 15mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5k $\Omega$ CS=100pF 1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

# 15. Backlight Information

### **Specification**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	16	20	30	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	_
Reverse Voltage	VR	_	_	5	V	_
Luminous Intensity	IV	130	160	_	CD/M <sup>2</sup>	ILED=20mA
Wave Length	λр			_	nm	ILED=20mA
Life Time	_	_	50K	_	Hr.	ILED≤20mA
Color	White	•	•	•	•	

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

# 16. Inspection specification

NO	Item	Criterion							
01	Electrical Testing	<ol> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> </ol>							
02	Black or white spots on LCD (display only)	<ul> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm</li> </ul>							
03	LCD black spots, white spots,	3.1 Round type : As following drawing $\Phi = (x + y) / 2$ $X \qquad \qquad \Phi \leq 0.10 \qquad \text{Accept no dense}$ $0.10 < \Phi \leq 0.20 \qquad 2$ $0.20 < \Phi \leq 0.25 \qquad 1$ $0.25 < \Phi \qquad \qquad 0$	2.5						
	contamination (non-display)	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5						
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5						

NO	Item	Criterion	AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination	
			AQL 2.5
		$Z \le 1/2t$ Not over viewing area $x \le 1/8a$	
		$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	
		⊙ If there are 2 or more chips, x is the total length of each chip.	

NO	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:	
06	Glass	$\begin{array}{ c c c c c c }\hline y: Chip \ width & x: Chip \ length & z: Chip \ thickness \\ \hline y \le 0.5mm & x \le 1/8a & 0 < z \le t \\ \hline 6.2.2 \ Non-conductive \ portion: & & & & L \\ \hline & & & & & & & L \\ \hline & & & & & & & & & \\ \hline & & & & & & &$	2.5
		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or color wrong.</li> </ul>	0.65 2.5 0.65
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>	2.5 0.65
10	PCB · COB	<ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> </ul>	2.5 2.5 0.65 2.5 2.5 0.65 2.5
11	Soldering	<ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	<ul> <li>12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.</li> <li>12.2 No cracks on interface pin (OLB) of TCP.</li> <li>12.3 No contamination, solder residue or solder balls on product.</li> <li>12.4 The IC on the TCP may not be damaged, circuits.</li> <li>12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.</li> <li>12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.</li> <li>12.7 Sealant on top of the ITO circuit has not hardened.</li> <li>12.8 Pin type must match type in specification sheet.</li> <li>12.9 LCD pin loose or missing pins.</li> <li>12.10 Product packaging must the same as specified on packaging specification sheet.</li> <li>12.11 Product dimension and structure must conform to product specification sheet.</li> </ul>	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

Winstar LCM Sam	nple Estimate	e Feedback Sheet
Module Number :		Page: 1
1 · Panel Specification:		
1. Panel Type:	Pass	□ NG ,
2. View Direction:	Pass	□ NG ,
3. Numbers of Dots:	Pass	□ NG ,
4. View Area:	Pass	□ NG ,
5. Active Area:	Pass	□ NG ,
6. Operating Temperature:	Pass	□ NG ,
7. Storage Temperature:	Pass	□ NG ,
8. Others:		
2 · Mechanical Specification :		
1. PCB Size:	Pass	□ NG ,
2. Frame Size:	Pass	□ NG ,
3. Materal of Frame:	Pass	□ NG ,
4. Connector Position:	Pass	□ NG ,
5. Fix Hole Position:	Pass	□ NG ,
6. Backlight Position:	Pass	□ NG ,
7. Thickness of PCB:	Pass	□ NG ,
8. Height of Frame to PCB:	Pass	□ NG ,
9. Height of Module:	Pass	□ NG ,
10. Others:	Pass	□ NG ,
3 · Relative Hole Size :		
1. Pitch of Connector:	Pass	☐ NG ,
2. Hole size of Connector:	Pass	☐ NG ,
3. Mounting Hole size:	Pass	☐ NG ,
4. Mounting Hole Type:	Pass	□ NG ,
5. Others:	Pass	☐ NG ,
4 \ Backlight Specification :		
1. B/L Type:	Pass	☐ NG ,
2. B/L Color:	Pass	☐ NG ,
3. B/L Driving Voltage (Refere	ence for LED T	ype):   Pass   NG,
4. B/L Driving Current:	Pass	☐ NG ,
5. Brightness of B/L:	Pass	☐ NG ,
6. B/L Solder Method:	Pass	☐ NG ,
7. Others:	Pass	☐ NG ,

>> Go to page 2 <<

Winstar LCM Samp	le Estimate Fe	eedback Sheet
dule Number :		Page: 2
· Electronic Characteristics o	f Module	
1. Input Voltage:	Pass	□ NG ,
2. Supply Current:	Pass	□ NG ,
3. Driving Voltage for LCD:	Pass	□ NG ,
. Contrast for LCD:	Pass	□ NG ,
5. B/L Driving Method:	Pass	□ NG ,
6. Negative Voltage Output:	Pass	□ NG ,
Interface Function:	Pass	□ NG ,
LCD Uniformity:	Pass	□ NG ,
ESD test:	Pass	☐ NG ,
Others:	Pass	☐ NG ,
Sales signature: Customer Signature:		<b>Date:</b> / /